

**RESIN COMPOSITION FOR SEALING SEMICONDUCTOR,
SEMICONDUCTOR DEVICE USING THE SAME,
SEMICONDUCTOR WAFER AND
MOUNTED STRUCTURE OF SEMICONDUCTOR DEVICE**

ABSTRACT

A resin composition for sealing a semiconductor device comprising (A) an epoxy resin; (B) a phenolic resin; and (C) a latent curing accelerator, wherein
5 the resin composition is a solid at 25°C or has a viscosity of not less than 400 Pa•s at 25°C and of not more than 200 Pa•s at 80°C; and a semiconductor device is obtained by mounting and sealing semiconductor elements on a wiring circuit substrate by using the resin composition.